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# **PRODUCT CHANGE NOTICE**

**Alternate Manufacturing Site  
for Assembly of Intersil  
Product ISL6265CHRTZ\***

**Refer to:  
PCN10120**

**Date: November 22, 2010**

November 22, 2010

To: Our Valued Intersil Customer

Subject: **Alternate Manufacturing Site for Assembly of Intersil Product ISL6265CHRTZ\* –  
STATS ChipPAC Malaysia**

This notice is to inform you that Intersil will begin using the STATS ChipPAC Malaysia (SCM) facility as alternate site for assembly of the listed ISL6265CHRTZ\* products. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The product and site-specific qualification activities are complete.

Products affected: **ISL6265CHRTZ ISL6265CHRTZ-T**

The STATS ChipPAC Malaysia (SCM) facility is ISO 9001:2000 and ISO/TS 16949:2009 certified and currently qualified as a supplier to Intersil for assembly of QFN packaged products. There will be no change in the package outline drawing (POD) or the moisture sensitivity level (MSL). The qualified material set combinations are as follows:

Material	Current	SCM
Mold Compound	Sumitomo EME-G770H	Sumitomo EME-G770
Die Attach	Hysol QMI 519	Ablebond A8290

The assembly qualification activity is considered QBE (Qualified by Extension) as the existing processes, materials, and equipment used to assemble the current QFN products at SCM will be used for this product going forward. The reliability QBE summary is included for reference. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at SCM may also be identified by the assembly site code (country of assembly) when marked on the devices. The assembly site code for the SCM facility is "H".

Intersil will take all necessary actions to conform to customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product manufactured at the either the current or the newly qualified sites beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

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PCN10120

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# PCN10120 – Reliability QBE Summary

## Package Reliability: 6x6 QFN SCM

Test Name	Lot ID	Mkt Num	Pkg	Compound	Precon.	Conditions	Duration	Sample Size	Rejects
AUTOCLAVE	SCM-M9G43007FCH000-2	ISL6312CRZ-T	48 LEAD 7X7 QFN	SG770	L3 PBFREE	121C, 100%RH	96	22	0
BOND INTEGRITY	SCM-QN100823G-LOT-C-0	ISL6265AHRTZ	48 LEAD 6X6 QFN	SG770	NONE	175C	96	5	0
BOND INTEGRITY	SCM-QN100823B-LOT-A-0	ISL6334ACRZ	40 LEAD 6X6 QFN	SG770	NONE	175C	96	5	0
BOND INTEGRITY	SCM-QN100823B-LOT-B-0	ISL6334ACRZ	40 LEAD 6X6 QFN	SG770	NONE	175C	96	5	0
BOND INTEGRITY	SCM-QN100823B-LOT-C-0	ISL6334ACRZ	40 LEAD 6X6 QFN	SG770	NONE	175C	96	5	0
BOND INTEGRITY	SCM-QN100823G-LOT-A-0	ISL6265AHRTZ	48 LEAD 6X6 QFN	SG770	NONE	175C	96	5	0
BOND INTEGRITY	SCM-QN100823G-LOT-B-0	ISL6265AHRTZ	48 LEAD 6X6 QFN	SG770	NONE	175C	96	5	0
HAST UNBIAS	SRN070040-0	ISL6324IRZ	48 LEAD 7X7 QFN	SG770	L2 PBFREE	130C, 85%RH	96	78	0
HAST UNBIAS	SRN070040-1	ISL6324IRZ	48 LEAD 7X7 QFN	SG770	L3 PBFREE	130C, 85%RH	96	78	0
TEMP CYCLE	SRN070040-0	ISL6324IRZ	48 LEAD 7X7 QFN	SG770	L2 PBFREE	-40C TO 125C	1000	78	0
TEMP CYCLE	SRN070040-1	ISL6324IRZ	48 LEAD 7X7 QFN	SG770	L3 PBFREE	-65C TO 150C	200	78	0
TEMP CYCLE	SCM-M9G43007FCH000-2	ISL6312CRZ-T	48 LEAD 7X7 QFN	SG770	L3 PBFREE	-65C TO 150C	500	22	0

## PCN10120 – Reliability QBE Summary –cont.

### Moisture Sensitivity Level:

Lot	Market #	Style	Die Size	Mold Compound	Die Attach	MSL	Reflow Temp
SCM-M9G43007FCH000	ISL6312CRZ-T	48 LEAD 7X7 QFN	121x134	SG770	A8290	3	260
SCM-QN100823B-LOT-A	ISL6334ACRZ	40 LEAD 6X6 QFN	91x92	SG770	A8290	3	260
SCM-QN100823B-LOT-B	ISL6334ACRZ	40 LEAD 6X6 QFN	91x92	SG770	A8290	3	260
SCM-QN100823B-LOT-C	ISL6334ACRZ	40 LEAD 6X6 QFN	91x92	SG770	A8290	3	260
SCM-QN100823G-LOT-A	ISL6265AHRTZ	48 LEAD 6X6 QFN	120x116	SG770	A8290	3	260
SCM-QN100823G-LOT-B	ISL6265AHRTZ	48 LEAD 6X6 QFN	120x116	SG770	A8290	3	260
SCM-QN100823G-LOT-C	ISL6265AHRTZ	48 LEAD 6X6 QFN	120x116	SG770	A8290	3	260
QN100923 LOT-A	ISL6265CHRTZ	48 LEAD 6X6 QFN	116x115	SG770	A8290	3	260
QN100923 LOT-B	ISL6265CHRTZ	48 LEAD 6X6 QFN	116x115	SG770	A8290	3	260
QN100923 LOT-C	ISL6265CHRTZ	48 LEAD 6X6 QFN	116x115	SG770	A8290	3	260